



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Moon et al.

Serial No.: 09/874,631

Filed: June 5, 2001

**For: FLEXIBLE BALL GRID ARRAY CHIP
SCALE PACKAGES AND METHODS OF
FABRICATION**

Examiner: Unknown

Group Art Unit: Unknown

Attorney Docket No.: 4368US(99-0959)

*#3/Pat-a
w/ Sub Spec
late*

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PRELIMINARY AMENDMENT

Box Non-Fee Amendment
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Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.